

**Call for Papers**  
**for a special issue of *Microelectronic Engineering***

**Micro- and Nano-Patterning**  
**Short title:  $\mu$ nP 2016**

**including selected papers from the**  
**42<sup>nd</sup> Micro- and Nano-Engineering conference [MNE 2016](#)**

The aim of this special issue is to bring together recent advances in Micro- and Nano-Patterning. This issue is 'open call'. This means that, while mainly including selected papers presented at MNE 2016, it is also open to other authors.

The MNE conference series focuses on micro- & nanofabrication and manufacturing using lithography and other approaches related to micro- and nanopatterning, as well as the application of micro- and nanostructures and devices in electronics, photonics, electromechanics, environment, and life sciences.

The areas of particular interest for this special issue are:

**Micro- and Nano-Patterning**

- **Photon lithography:** DUV, EUV, immersion, sources, optics, mask technology, alignment, optical proximity correction, modelling, throughput, multiple exposure
- **Electron and ion beam lithography:** sources, optics, systems, alignment, proximity, corrections, modelling, ion and electron beam - surface interactions, direct write, mask technology
- **Other patterning techniques:** stencil based patterning, directed self-assembly, tip- and scanning-probe-based techniques, novel techniques
- **Materials and techniques for micro- and nano-patterning:** resists, resist processing, resist structure, stamps, block copolymers, surface functionalization
- **Pattern transfer:** plasma etching, lift-off, sputtering, milling, nanoscale etching, deep etching, directional (lateral) etching, other techniques for patterning

**Manuscript submission deadline: 14 October 2016**

Manuscripts of the special issues will be submitted and reviewed via the online Elsevier Editorial System (EES). Articles will be processed and published with the standard Elsevier publishing timeline for each individual manuscript following acceptance. Please submit papers directly using the [MEE journal submission web page](#) and select the appropriate special issue. The submission opens on 7 September 2016.

**Guest Editors**

[Hermann Detz](#) (Vienna University of Technology, Austria)

[Heinz Wanzenböck](#) (Vienna University of Technology, Austria)

**Instructions for authors**

- The standard submitted manuscripts are regular MEE publications (4-6 pages).
- Review papers (7-10 pages) are encouraged from invited/plenary speakers and leading members of the community. If you are not an MNE invited speaker and you wish to submit a review, please contact [Evangelos Gogolides](#) (Editor-in-Chief, Microelectronic Engineering) or one of the Guest Editors with a proposal and outline.
- Highly novel work can be submitted as an *accelerated* publication (up to 4 pages) and will be given high priority.
- For all publications, we encourage you to include supplementary data and audio/video abstracts.
- For general enquiries, please contact the [MNE Program Chair](#).
- Please select the correct file type (regular paper, review paper, etc.) and choose the correct name of the special issue  **$\mu$ nP 2016**.

Your paper and associated supplementary information should comprise a complete, novel and full description of your work. Please make sure that your paper is well-written, and supply additional information, videos, audios, etc. as on-line supplementary material to appear on the web, but not in the printed version (see instructions for authors). Your supplementary material will be available directly from ScienceDirect or Scopus.

Please note that the special issue papers undergo the same high-standard review process as any other MEE paper. At least two reviews need to be in agreement per paper before decision, and the typical rejection rate is 50-60%. Therefore, please make sure that both the technical content of your paper, and your presentation style and language, is of high quality, novel, unpublished, and not being submitted elsewhere. Please check the [author guidelines](#).